

Title (en)
METHODS FOR CLEANING MICROELECTRONIC STRUCTURES

Title (de)
VERFAHREN ZUR REINIGUNG VON MIKROELEKTRONISCHEN STRUKTUREN

Title (fr)
PROCEDES DE NETTOYAGE DE STRUCTURES MICROELECTRONIQUES

Publication
EP 1368136 A4 20051012 (EN)

Application
EP 02724947 A 20020214

Priority

- US 0204398 W 20020214
- US 26902601 P 20010215
- US 93206301 A 20010817
- US 95125901 A 20010913
- US 95124901 A 20010913
- US 95109201 A 20010913
- US 95124701 A 20010913

Abstract (en)
[origin: WO02066176A1] A method of cleaning and removing water, entrained solutes and particulate matter during a manufacturing process from a microelectronic device comprises the steps of: (a) providing a partially fabricated integrated circuit, MEM's device, or optoelectronic device having water and entrained solutes on the substrate; (b) providing a densified carbon dioxide cleaning composition, the cleaning composition comprising carbon dioxide and, optionally but preferably, a cleaning adjunct; (c) immersing the surface portion in the densified carbon dioxide drying composition; and then (d) removing the cleaning composition from the surface portion.

IPC 1-7
B08B 3/00; **F26B 3/00**; **G03F 7/42**; **H01L 21/00**

IPC 8 full level
G03F 7/32 (2006.01); **B08B 7/00** (2006.01); **H01L 21/027** (2006.01); **H01L 21/304** (2006.01); **H01L 21/306** (2006.01)

CPC (source: EP KR)
B08B 7/0021 (2013.01 - EP); **H01L 21/02063** (2013.01 - EP); **H01L 21/304** (2013.01 - KR)

Citation (search report)

- No further relevant documents disclosed
- See references of WO 02066176A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
WO 02066176 A1 20020829; CN 1628000 A 20050615; EP 1368136 A1 20031210; EP 1368136 A4 20051012; JP 2004527110 A 20040902; KR 20030075185 A 20030922

DOCDB simple family (application)
US 0204398 W 20020214; CN 02804975 A 20020214; EP 02724947 A 20020214; JP 2002565725 A 20020214; KR 20037010495 A 20030808